

LINEAR TECHNOLOGY MATERIALS DECLARATION

1tc1384csw#trpbf

(Engineering Calculation)

SOIC WIDE

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TOTAL MASS (g) : 0.51201

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.003860 | 1000000 | 7538.92041016 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.161470 | 975000 | 315365.125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.003975 | 24000 | 7763.52539062 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000050 | 300 | 97.6544036865 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000116 | 700 | 226.55821228 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.165611 | 1000000 | 323452.875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.005671 | 1000000 | 11075.4404297 | | |
| | | External Plating Total: | | | | 0.005671 | 1000000 | 11075.4404297 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001325 | 1000000 | 2587.84155273 | | |
| Internal Plating Total: | | | | 0.001325 | 1000000 | 2587.84155273 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001080 | 750000 | 2109.33496094 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000360 | 250000 | 703.111694336 | | |
| Die Attach Total: | | | | 0.001440 | 1000000 | 2812.44677734 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.045043 | 135000 | 87972.9453125 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.286939 | 860000 | 560417.125 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.001668 | 5000 | 3257.75097656 | | |
| | | Encapsulation Total: | | | | 0.333650 | 1000000 | 651647.8125 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000453 | 1000000 | 884.748901367 | | |
| | | | | | TOTAL MASS (g) : | 0.51201 | | |